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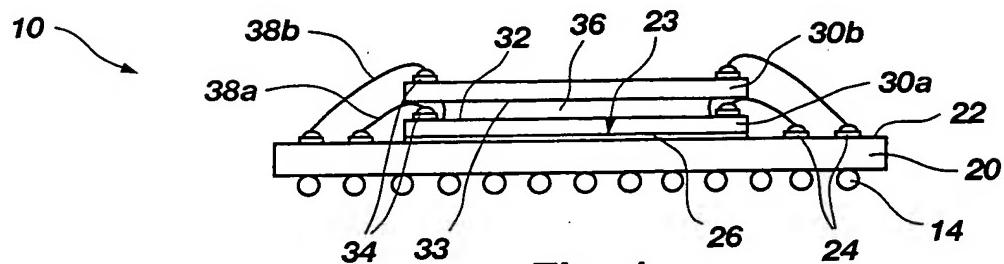


Fig. 1

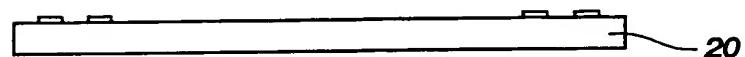


Fig. 2

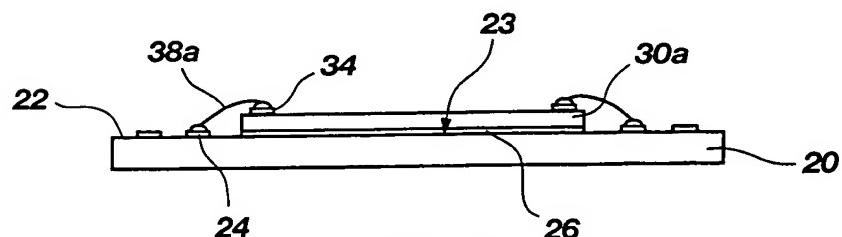


Fig. 3

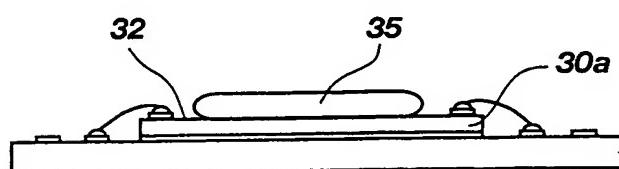


Fig. 4

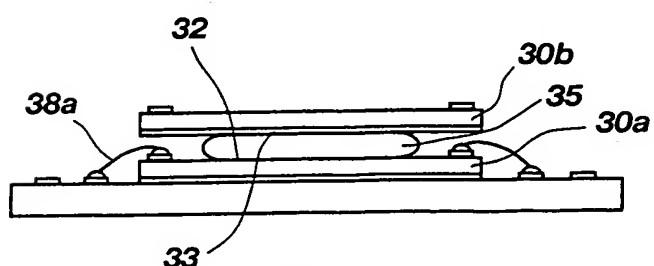
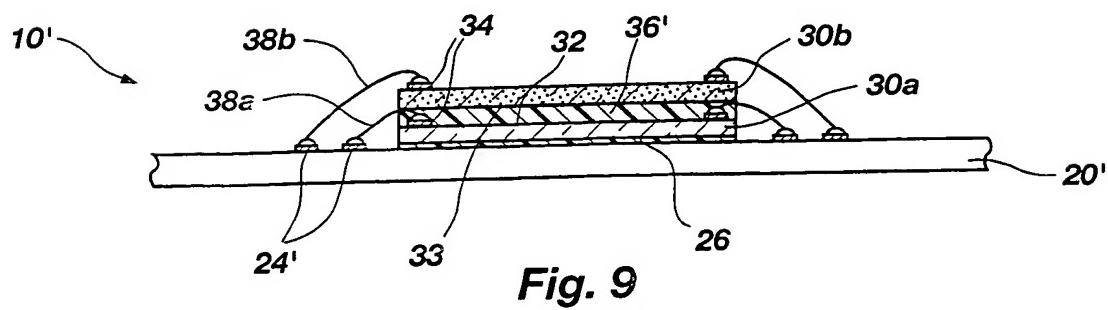
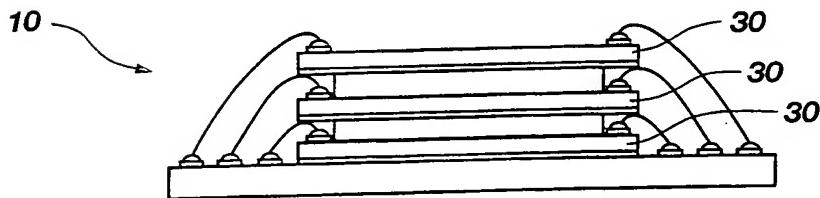
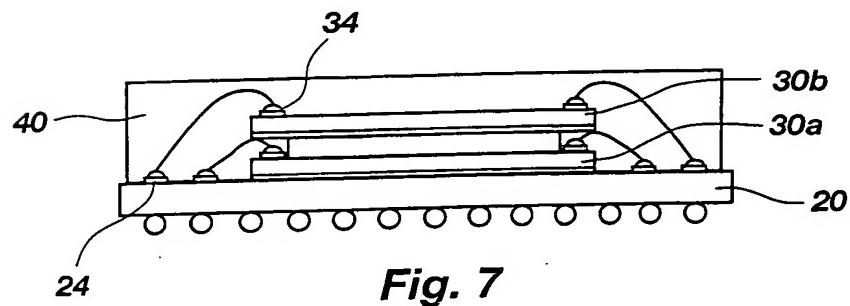
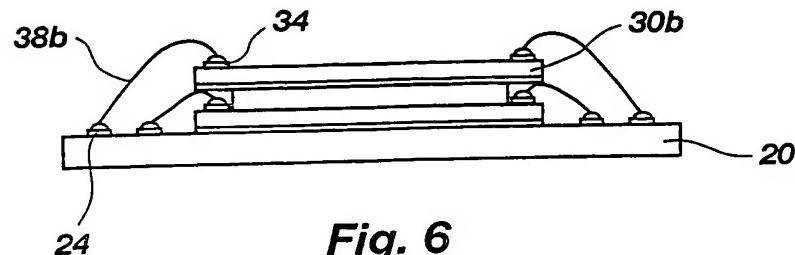


Fig. 5

TITLE: METHODS FOR FORMING ASSEMBLIES AND PACKAGES
THAT INCLUDE STACKED SEMICONDUCTOR DEVICES
SEPARATED A DISTANCE DEFINED BY ADHESIVE MATERIAL
INTERPOSED THEREBETWEEN

Inventor: J. Derderian
Docket No.: 2269-4817.3US

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TITLE: METHODS FOR FORMING ASSEMBLIES AND PACKAGES
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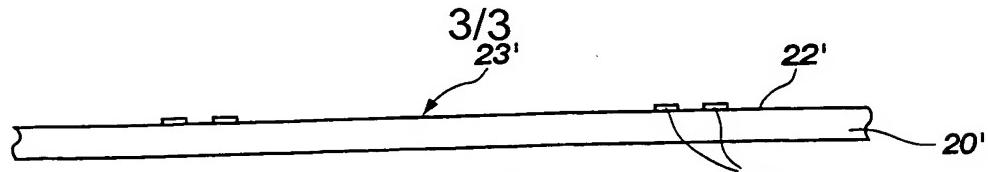


Fig. 10

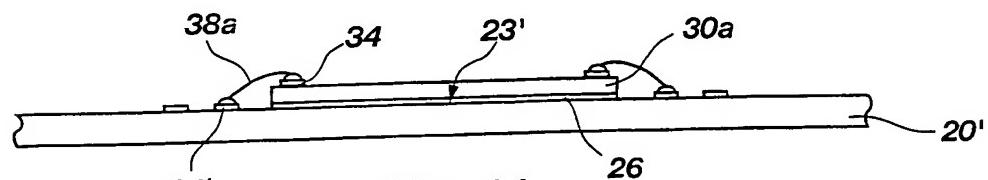


Fig. 11

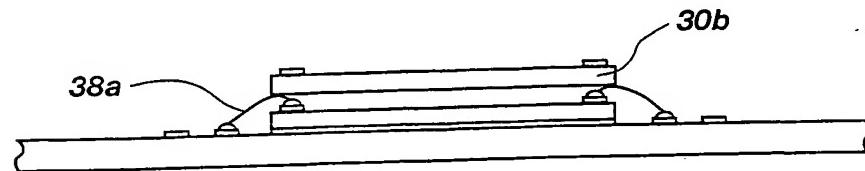


Fig. 12

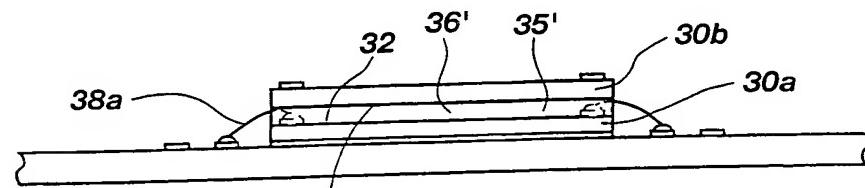


Fig. 13



Fig. 14

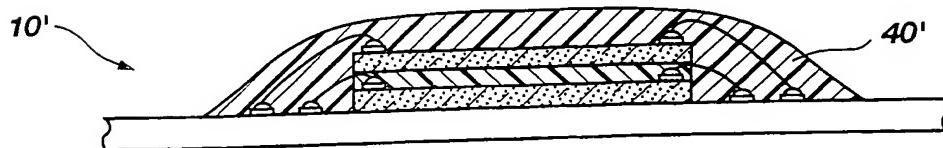


Fig. 15

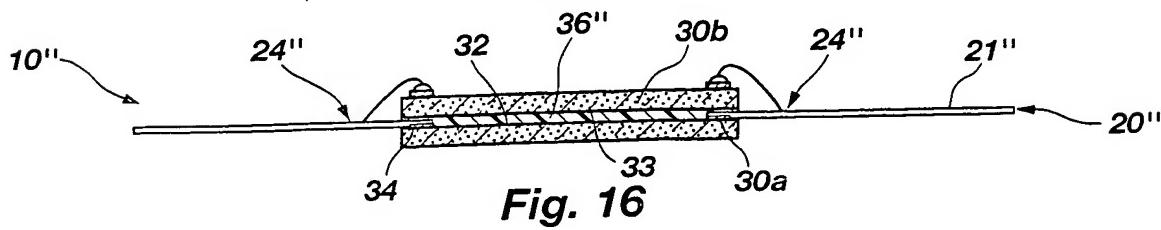


Fig. 16